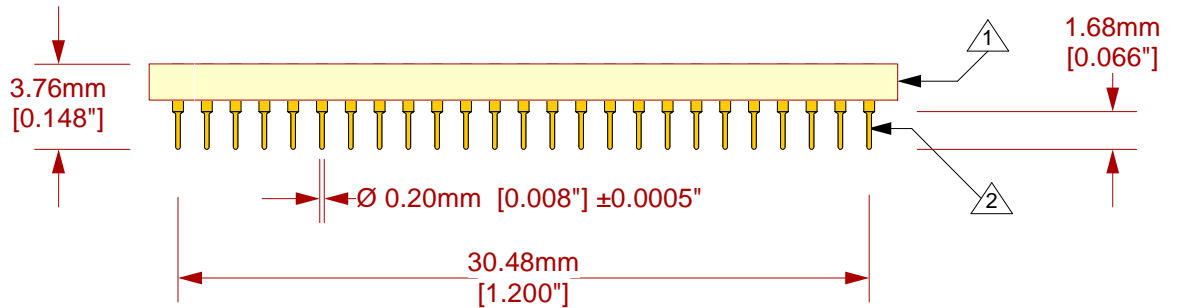


Side View




① Substrate: 1.59mm $\pm 0.18\text{mm} [0.0625" \pm 0.007"]$
FR4/G10 or equivalent high temp material.

② Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25 $\mu\text{m} [10\mu"]$ Au over 1.27 $\mu\text{m} [50\mu"]$ Ni (min.).

Description: Giga-snaP BGA SMT Land Socket

503 position BGA surface mount land pattern to terminal pins (1.27mm [0.050"] centers, 25x25 array)

Tolerances: diameters $\pm 0.03\text{mm} [\pm 0.001"]$, PCB perimeters $\pm 0.13\text{mm} [\pm 0.005"]$, PCB thicknesses $\pm 0.18\text{mm} [\pm 0.007"]$, pitches (from true position) $\pm 0.08\text{mm} [\pm 0.003"]$, all other tolerances $\pm 0.13\text{mm} [\pm 0.005"]$ unless stated otherwise. Materials and specifications are subject to change without notice.

	LS-BGA503C-31 Drawing		Status: Released	Scale: 3:1	Rev: A
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr., Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com		Drawing: J. Glab		Date: 05/25/07
			File: LS-BGA503C-31 Dwg		Modified: